Light Emitting Diodes

Panasonic

LN11WP23

Round Type

φ5.0 mm

Absolute Maximum Ratings $T_a = 25^{\circ}C$

• Red	
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Parameter	Symbol	Symbol Rating	
Power dissipation	P _D	70	mW
Forward current	I _F	25	mA
Pulse forward current *	I _{FP}	150	mA
Reverse voltage	V _R	4	V
Operating ambient temperature	T _{opr}	-25 to +85	°C
Storage temperature	T _{stg}	-30 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Yellow Green

Parameter	Symbol	Rating	Unit	
Power dissipation	PD	90	mW	
Forward current	I _F	30	mA	
Pulse forward current *	I _{FP}	150	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to $+100$	°C	

Note) *: The condition of IFP is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

• Red							
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity		Io	"THE	1.0	3.0		mcd
Reverse current		IR	$V_R = 4 V$			10	μΑ
Forward voltage	N.	V _F	$I_F = 20 \text{ mA}$		2.2	2.8	V
Peak emission wavelength	2	λρ	$I_F = 20 \text{ mA}$		700		nm
Spectral half band width	aller	Δλ	$I_F = 20 \text{ mA}$		100		nm
	6						

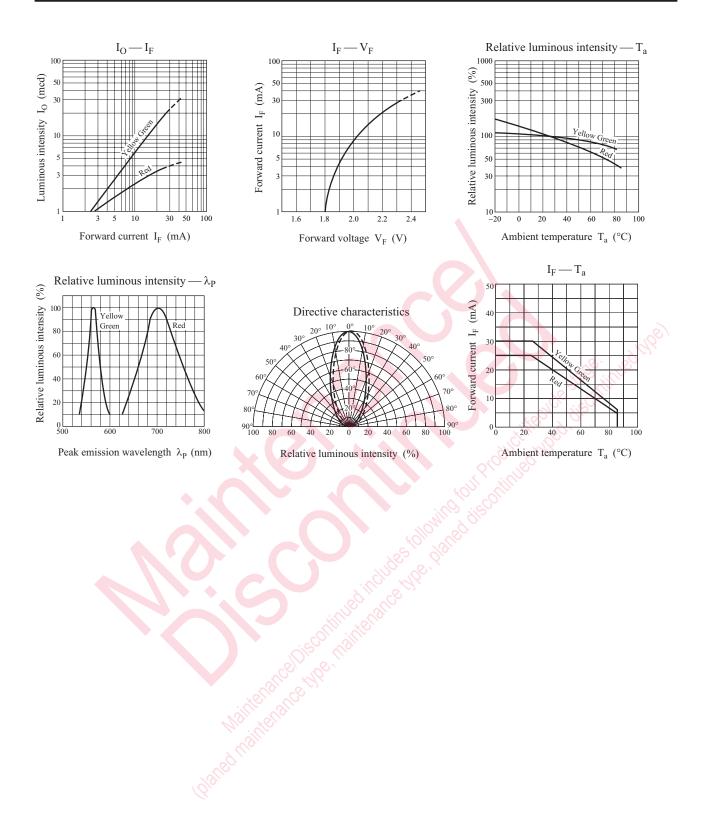
• Yellow Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		3.0	15.0		mcd
Reverse current	I _R	$V_R = 4 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 20 {\rm mA}$		2.2	2.8	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 20 \ {\rm mA}$		565		nm
Spectral half band width	Δλ	$I_{\rm F} = 20 {\rm mA}$		30		nm

Lighting Color

Red Yellow Green

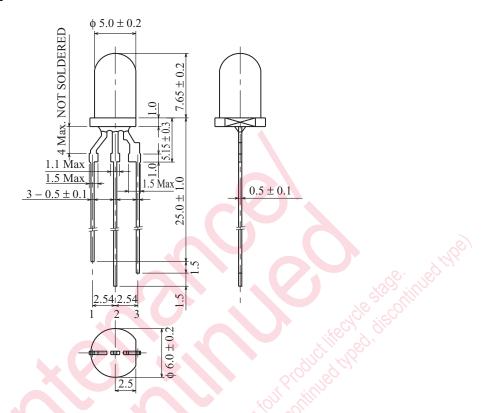
Panasonic



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Package (Unit: mm)

LLXLTN3SH012



• Pin name

- 1: Anode (Yellow Green)
- 2: Cathode (Common)
- 3: Anode (Red)

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